IN THE SPECIFICATION

Please replace line 25 at page 18, with the following rewritten line:

26, [[26a,]] 26b, 26c Conductive pats for high-frequency shielding

Please replace line 7 at page 19, with the following rewritten line:

35 [[Top]] Bottom force

Please replace the paragraph at page 62, lines 1-5, with the following rewritten paragraph:

A clearance between conductive parts 26 for high-frequency shielding adjoining each other, which surrounds the respective conductive parts [[25]] 22 for connection, is the same as in the anisotropically conductive connector 10 according to the second embodiment.

Please replace the paragraph at page 65, lines 2-7, with the following rewritten paragraph:

Projected parts 22a and 26a protruding from other surfaces than portions, at which the conductive parts 22 for connection and the conductive part 26 for high-frequency shielding are located, are formed at those portions on both surfaces of the functional part 21 in the elastic anisotropically conductive film 20.

Please replace the paragraph at page 68, line 23 to page 69, line 1, with the following rewritten paragraph:

Projected parts 22a and 26a protruding from other surfaces than portions, at which the conductive parts 22 for connection and the conductive parts 26 for high-frequency shielding

are located, are formed at those portions on both surfaces of the functional part 21 in the elastic anisotropically conductive film 20.

Please replace the paragraph at page 78, lines 6-19, with the following rewritten paragraph:

For example, in addition to conductive parts [[26a]] <u>26</u> for high-frequency shielding, which surround individual conductive parts 22 for connection, conductive parts 26b for high-frequency shielding, which surround a group of conductive parts including a plurality of conductive parts 22 for connection, may be additionally formed in the functional part 21 of the elastic anisotropically conductive film 20 as illustrated in Fig. 26. In addition to conductive parts [[26a]] <u>26</u>, 26b for high-frequency shielding formed in the functional part 21, conductive parts 26c for high-frequency shielding, which surround a group of conductive parts including a plurality of conductive parts 22 for connection, may be additionally formed in the part 28 to be supported as illustrated in Fig. 27.

Please replace the paragraph at page 88, line 25 to page 89, line 11, with the following rewritten paragraph:

In the elastic anisotropically conductive film (20) in the anisotropically conductive connector (10) thus obtained, 16 (4 x 4) conductive parts (22) for connection are formed, and a center distance (pitch) between adjacent conductive parts (22) for connection is 1 mm. Each of the conductive parts (22) for connection is such that the diameter is 300 µm, the thickness is 400 µm, and the projected heights from both surfaces of the insulating part (23) are each 50 µm. Each of the conductive parts (26) for high-frequency shielding is such that the inner diameter is 600 µm, the outer diameter is 800 µm, the thickness is [[150]] 400 µm.

and the projected heights from both surfaces of the insulating part (23) are each 50 μm . The thickness of the insulating part (23) is 300 μm .

Please cancel the original Abstract at page 104, lines 1-20 in its entirety, and insert therefor the following replacement Abstract on a separate sheet as follows: